



**128K X 36  
3.3V Synchronous SRAMs  
2.5V I/O, Pipelined Outputs,  
Burst Counter, Single Cycle Deselect**

**IDT71V25761YS/S**

## Features

- ◆ 128K x 36 memory configuration
- ◆ Supports high system speed:
  - Commercial:*
    - 200MHz 3.1ns clock access time
  - Commercial and Industrial:*
    - 183MHz 3.3ns clock access time
    - 166MHz 3.5ns clock access time
- ◆ LBO input selects interleaved or linear burst mode
- ◆ Self-timed write cycle with global write control (**GW**), byte write enable (**BWE**), and byte writes (**BWx**)
- ◆ 3.3V core power supply
- ◆ Power down controlled by ZZ input
- ◆ 2.5V I/O
- ◆ Optional - Boundary Scan JTAG Interface (IEEE 1149.1 Compliant)
- ◆ Packaged in a JEDEC Standard 100-pin plastic thin quad flatpack (TQFP), 119 ball grid array (BGA) and 165 fine pitch ball grid array

## Description

The IDT71V25761 are high-speed SRAMs organized as 128K x 36. The IDT71V25761 SRAMs contain write, data, address and control registers. Internal logic allows the SRAM to generate a self-timed write based upon a decision which can be left until the end of the write cycle.

The burst mode feature offers the highest level of performance to the system designer, as the IDT71V25761 can provide four cycles of data for a single address presented to the SRAM. An internal burst address counter accepts the first cycle address from the processor, initiating the access sequence. The first cycle of output data will be pipelined for one cycle before it is available on the next rising clock edge. If burst mode operation is selected (**ADV=LOW**), the subsequent three cycles of output data will be available to the user on the next three rising clock edges. The order of these three addresses are defined by the internal burst counter and the **LBO** input pin.

The IDT71V25761 SRAMs utilize IDT's latest high-performance CMOS process and are packaged in a JEDEC standard 14mm x 20mm 100-pin thin plastic quad flatpack (TQFP) as well as a 119 ball grid array (BGA) and 165 fine pitch ball grid array (fBGA).

## Pin Description Summary

Pin Name	Function	Input/Output	Timing
A0-A17	Address Inputs	Input	Synchronous
<b>CE</b>	Chip Enable	Input	Synchronous
<b>CS0</b> , <b>CS1</b>	Chip Selects	Input	Synchronous
<b>OE</b>	Output Enable	Input	Asynchronous
<b>GW</b>	Global Write Enable	Input	Synchronous
<b>BWE</b>	Byte Write Enable	Input	Synchronous
<b>BW1</b> , <b>BW2</b> , <b>BW3</b> , <b>BW4</b> <sup>(1)</sup>	Individual Byte Write Selects	Input	Synchronous
<b>CLK</b>	Clock	Input	N/A
<b>ADV</b>	Burst Address Advance	Input	Synchronous
<b>ADSC</b>	Address Status (Cache Controller)	Input	Synchronous
<b>ADSP</b>	Address Status (Processor)	Input	Synchronous
<b>LBO</b>	Linear / Interleaved Burst Order	Input	DC
<b>TMS</b>	Test Mode Select	Input	Synchronous
<b>TDI</b>	Test Data Input	Input	Synchronous
<b>TCK</b>	Test Clock	Input	N/A
<b>TDO</b>	Test Data Output	Output	Synchronous
<b>TRST</b>	JTAG Reset (Optional)	Input	Asynchronous
<b>ZZ</b>	Sleep Mode	Input	Asynchronous
I/O0-I/O31, I/OP1-I/O4	Data Input / Output	I/O	Synchronous
<b>VDD</b> , <b>VDDQ</b>	Core Power, I/O Power	Supply	N/A
<b>VSS</b>	Ground	Supply	N/A

5297 fb 01

JULY 2014

## Pin Definitions<sup>(1)</sup>

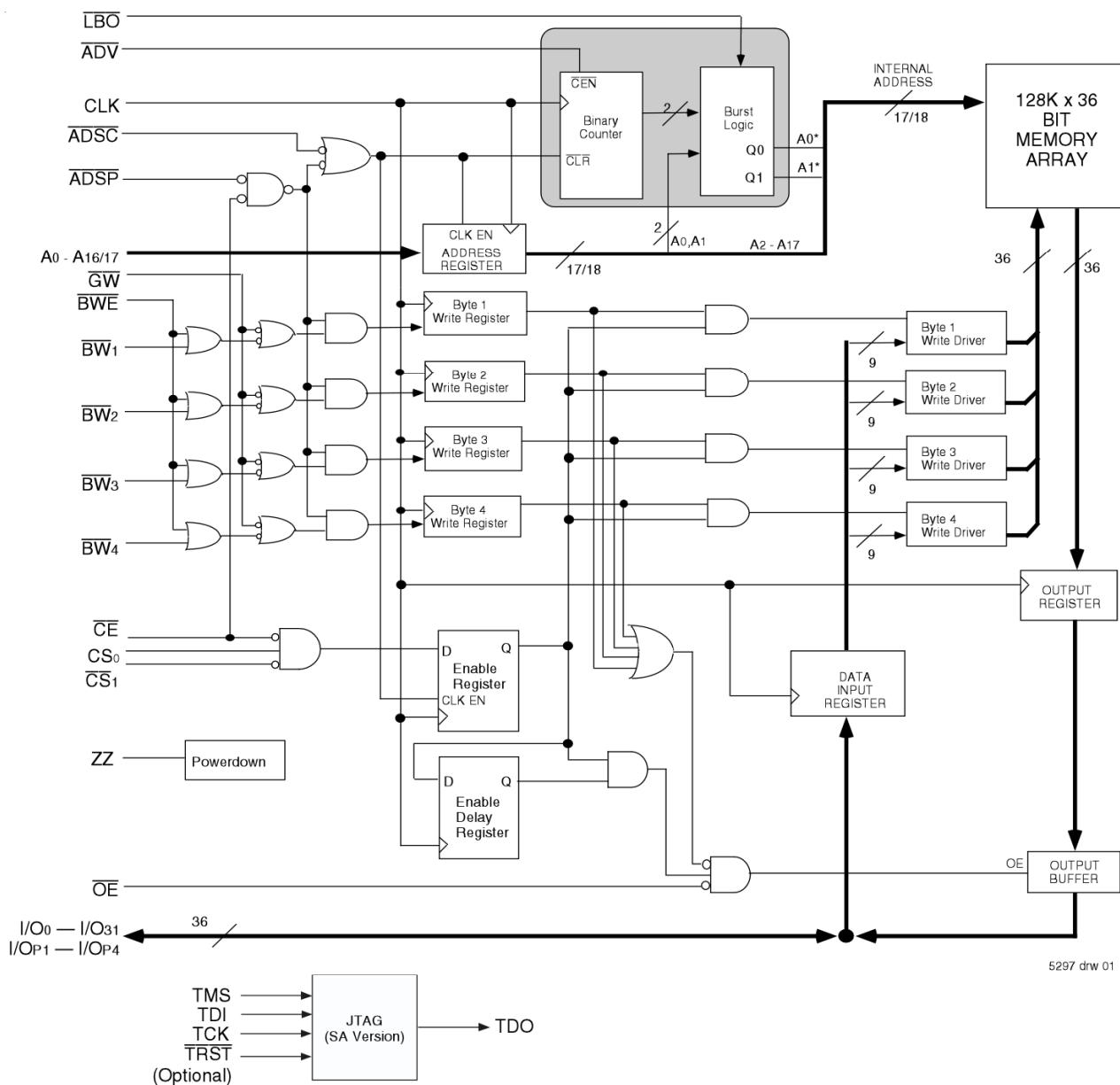
Symbol	Pin Function	I/O	Active	Description
A0-A17	Address Inputs	I	N/A	Synchronous Address inputs. The address register is triggered by a combination of the rising edge of CLK and $\overline{ADSC}$ Low or $\overline{ADSP}$ Low and $\overline{CE}$ Low.
$\overline{ADSC}$	Address Status (Cache Controller)	I	LOW	Synchronous Address Status from Cache Controller. $\overline{ADSC}$ is an active LOW input that is used to load the address registers with new addresses.
$\overline{ADSP}$	Address Status (Processor)	I	LOW	Synchronous Address Status from Processor. $\overline{ADSP}$ is an active LOW input that is used to load the address registers with new addresses. $\overline{ADSP}$ is gated by $\overline{CE}$ .
$\overline{ADV}$	Burst Address Advance	I	LOW	Synchronous Address Advance. $\overline{ADV}$ is an active LOW input that is used to advance the internal burst counter, controlling burst access after the initial address is loaded. When the input is HIGH the burst counter is not incremented; that is, there is no address advance.
$\overline{BWE}$	Byte Write Enable	I	LOW	Synchronous byte write enable gates the byte write inputs $\overline{BW1}$ - $\overline{BW4}$ . If $\overline{BWE}$ is LOW at the rising edge of CLK then $\overline{BWx}$ inputs are passed to the next stage in the circuit. If $\overline{BWE}$ is HIGH then the byte write inputs are blocked and only $\overline{GW}$ can initiate a write cycle.
$\overline{BW1}$ - $\overline{BW4}$	Individual Byte Write Enables	I	LOW	Synchronous byte write enables. $\overline{BW1}$ controls I/O0-7, I/O1, $\overline{BW2}$ controls I/O8-15, I/O2, etc. Any active byte write causes all outputs to be disabled.
$\overline{CE}$	Chip Enable	I	LOW	Synchronous chip enable. $\overline{CE}$ is used with CS0 and $\overline{CS1}$ to enable the IDT71V25761/781. $\overline{CE}$ also gates $\overline{ADSP}$ .
CLK	Clock	I	N/A	This is the clock input. All timing references for the device are made with respect to this input.
CS0	Chip Select 0	I	HIGH	Synchronous active HIGH chip select. CS0 is used with $\overline{CE}$ and $\overline{CS1}$ to enable the chip.
$\overline{CS1}$	Chip Select 1	I	LOW	Synchronous active LOW chip select. $\overline{CS1}$ is used with $\overline{CE}$ and CS0 to enable the chip.
$\overline{GW}$	Global Write Enable	I	LOW	Synchronous global write enable. This input will write all four 9-bit data bytes when LOW on the rising edge of CLK. $\overline{GW}$ supersedes individual byte write enables.
I/O0-I/O31 I/O1-I/O4	Data Input/Output	I/O	N/A	Synchronous data input/output (I/O) pins. Both the data input path and data output path are registered and triggered by the rising edge of CLK.
$\overline{LBO}$	Linear Burst Order	I	LOW	Asynchronous burst order selection input. When $\overline{LBO}$ is HIGH, the interleaved burst sequence is selected. When $\overline{LBO}$ is LOW the Linear burst sequence is selected. $\overline{LBO}$ is a static input and must not change state while the device is operating.
$\overline{OE}$	Output Enable	I	LOW	Asynchronous output enable. When $\overline{OE}$ is LOW the data output drivers are enabled on the I/O pins if the chip is also selected. When $\overline{OE}$ is HIGH the I/O pins are in a high-impedance state.
TMS	Test ModeSelect	I	N/A	Gives input command for TAP controller. Sampled on rising edge of TDI. This pin has an internal pullup.
TDI	Test Data Input	I	N/A	Serial input of registers placed between TDI and TDO. Sampled on rising edge of TCK. This pin has an internal pullup.
TCK	Test Clock	I	N/A	Clock input of TAP controller. Each TAP event is clocked. Test inputs are captured on rising edge of TCK, while test outputs are driven from the falling edge of TCK. This pin has an internal pullup.
TDO	Test DataOutput	O	N/A	Serial output of registers placed between TDI and TDO. This output is active depending on the state of the TAP controller.
$\overline{TRST}$	JTAG Reset (Optional)	I	LOW	Optional Asynchronous JTAG reset. Can be used to reset the TAP controller, but not required. JTAG reset occurs automatically at power up and also resets using TMS and TCK per IEEE 1149.1. If not used $\overline{TRST}$ can be left floating. This pin has an internal pullup. Only available in BGA package.
ZZ	Sleep Mode	I	HIGH	Asynchronous sleep mode input. ZZ HIGH will gate the CLK internally and power down the IDT71V25761/781 to its lowest power consumption level. Data retention is guaranteed in Sleep Mode. This pin has an internal pull down.
VDD	Power Supply	N/A	N/A	3.3V core power supply.
VDDQ	Power Supply	N/A	N/A	2.5V I/O Supply.
Vss	Ground	N/A	N/A	Ground.
NC	No Connect	N/A	N/A	NC pins are not electrically connected to the device.

NOTE:

- All synchronous inputs must meet specified setup and hold times with respect to CLK.

5297 Ibl 02

## Functional Block Diagram



Absolute Maximum Ratings<sup>(1)</sup>

Symbol	Rating	Commercial & Industrial	Unit
VTERM <sup>(2)</sup>	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
VTERM <sup>(3,6)</sup>	Terminal Voltage with Respect to GND	-0.5 to VDD	V
VTERM <sup>(4,6)</sup>	Terminal Voltage with Respect to GND	-0.5 to VDD +0.5	V
VTERM <sup>(5,6)</sup>	Terminal Voltage with Respect to GND	-0.5 to VDDQ +0.5	V
TA <sup>(7)</sup>	Commercial Operating Temperature	-0 to +70	°C
	Industrial Operating Temperature	-40 to +85	°C
TBIAS	Temperature Under Bias	-55 to +125	°C
TSTG	Storage Temperature	-55 to +125	°C
PT	Power Dissipation	2.0	W
IOUT	DC Output Current	50	mA

5297 tbl 03

## NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- VDD terminals only.
- VDDQ terminals only.
- Input terminals only.
- I/O terminals only.
- This is a steady-state DC parameter that applies after the power supplies have ramped up. Power supply sequencing is not necessary; however, the voltage on any input or I/O pin cannot exceed VDDQ during power supply ramp up.
- TA is the "instant on" case temperature.

## 100 pin TQFP Capacitance

(TA = +25°C, f = 1.0MHz)

Symbol	Parameter <sup>(1)</sup>	Conditions	Max.	Unit
CIN	Input Capacitance	VIN = 3dV	5	pF
CIO	I/O Capacitance	VOUT = 3dV	7	pF

5297 tbl 07b

## 165 fBGA Capacitance

(TA = +25°C, f = 1.0MHz)

Symbol	Parameter <sup>(1)</sup>	Conditions	Max.	Unit
CIN	Input Capacitance	VIN = 3dV	7	pF
CIO	I/O Capacitance	VOUT = 3dV	7	pF

5297 tbl 07b

## NOTE:

- This parameter is guaranteed by device characterization, but not production tested.

## Recommended Operating Temperature and Supply Voltage

Grade	Temperature <sup>(1)</sup>	VSS	VDD	VDDQ
Commercial	0°C to +70°C	0V	3.3V±5%	2.5V±5%
Industrial	-40°C to +85°C	0V	3.3V±5%	2.5V±5%

## NOTES:

5297 tbl 04

- TA is the "instant on" case temperature.

## Recommended DC Operating Conditions

Symbol	Parameter	Min.	Typ.	Max.	Unit
VDD	Core Supply Voltage	3.135	3.3	3.465	V
VDDQ	I/O Supply Voltage	2.375	2.5	2.625	V
VSS	Supply Voltage	0	0	0	V
VIH	Input High Voltage - Inputs	1.7	—	VDD +0.3	V
VIH	Input High Voltage - I/O	1.7	—	VDDQ +0.3 <sup>(1)</sup>	V
VIL	Input Low Voltage	-0.3 <sup>(2)</sup>	—	0.7	V

## NOTES:

5297 tbl 05

- VIH (max) = VDDQ + 1.0V for pulse width less than tcyc/2, once per cycle.
- VIL (min) = -1.0V for pulse width less than tcyc/2, once per cycle.

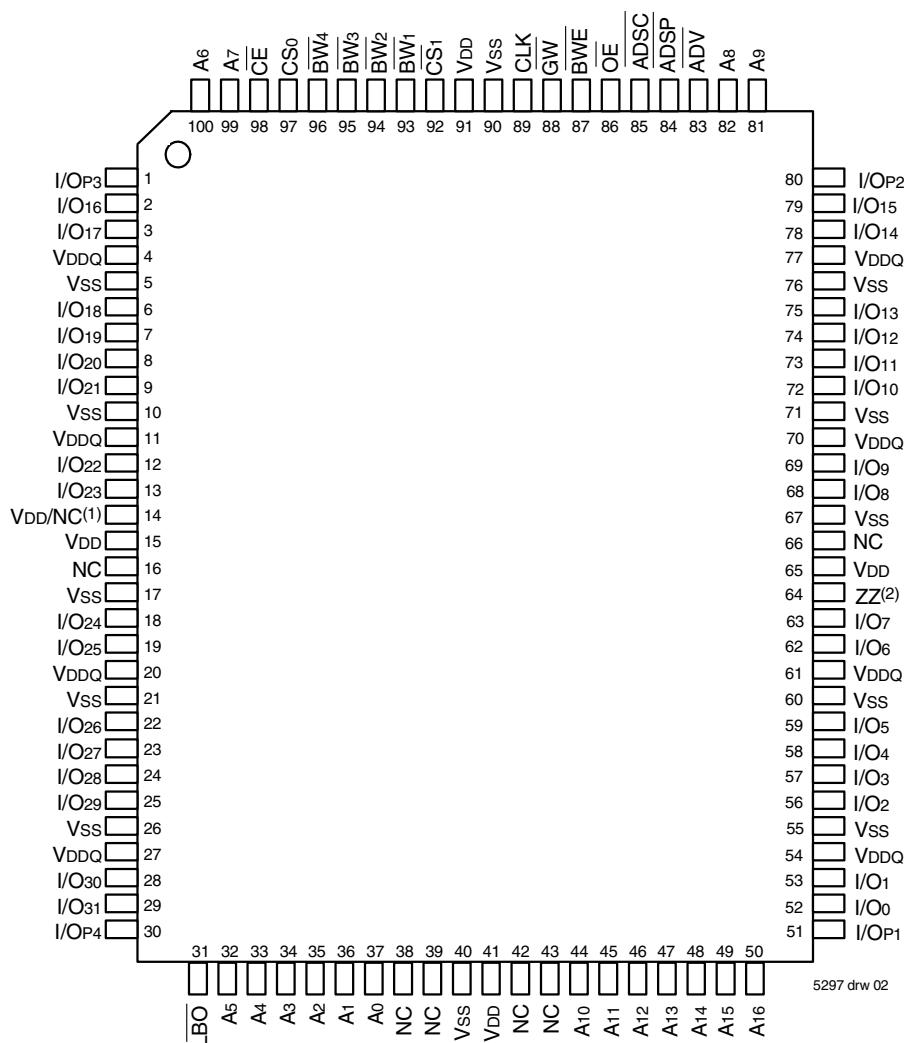
## 119 BGA Capacitance

(TA = +25°C, f = 1.0MHz)

Symbol	Parameter <sup>(1)</sup>	Conditions	Max.	Unit
CIN	Input Capacitance	VIN = 3dV	7	pF
CIO	I/O Capacitance	VOUT = 3dV	7	pF

5297 tbl 07a

## Pin Configuration – 128K x 36



100 TQFP  
Top View

### NOTES:

1. Pin 14 can either be directly connected to VDD, or connected to an input voltage  $\geq V_{IH}$ , or left unconnected.
2. Pin 64 can be left unconnected and the device will always remain in active mode.

## Pin Configuration – 128K x 36, 119 BGA

	1	2	3	4	5	6	7
A	VDDQ	A6	A4	ADSP	A8	A16	VDDQ
B	NC	CS <sub>0</sub>	A3	ADSC	A9	CS <sub>1</sub>	NC
C	NC	A7	A2	VDD	A12	A15	NC
D	I/O16	I/O <sub>3</sub>	VSS	NC	VSS	I/O <sub>2</sub>	I/O <sub>15</sub>
E	I/O <sub>17</sub>	I/O <sub>18</sub>	VSS	CE	VSS	I/O <sub>13</sub>	I/O <sub>14</sub>
F	VDDQ	I/O <sub>19</sub>	VSS	OE	VSS	I/O <sub>12</sub>	VDDQ
G	I/O <sub>20</sub>	I/O <sub>21</sub>	BW <sub>3</sub>	ADV	BW <sub>2</sub>	I/O <sub>11</sub>	I/O <sub>10</sub>
H	I/O <sub>22</sub>	I/O <sub>23</sub>	VSS	GW	VSS	I/O <sub>9</sub>	I/O <sub>8</sub>
J	VDDQ	VDD	NC	VDD	NC	VDD	VDDQ
K	I/O <sub>24</sub>	I/O <sub>26</sub>	VSS	CLK	VSS	I/O <sub>6</sub>	I/O <sub>7</sub>
L	I/O <sub>25</sub>	I/O <sub>27</sub>	BW <sub>4</sub>	NC	BW <sub>1</sub>	I/O <sub>4</sub>	I/O <sub>5</sub>
M	VDDQ	I/O <sub>28</sub>	VSS	BWE	VSS	I/O <sub>3</sub>	VDDQ
N	I/O <sub>29</sub>	I/O <sub>30</sub>	VSS	A <sub>1</sub>	VSS	I/O <sub>2</sub>	I/O <sub>1</sub>
P	I/O <sub>31</sub>	I/O <sub>4</sub>	VSS	A <sub>0</sub>	VSS	I/O <sub>0</sub>	I/O <sub>1</sub>
R	NC	A <sub>5</sub>	LBO	VDD	VDD / NC <sup>(1)</sup>	A <sub>13</sub>	NC
T	NC	NC	A <sub>10</sub>	A <sub>11</sub>	A <sub>14</sub>	NC	ZZ <sup>(3)</sup>
U	VDDQ	NC/TMS <sup>(2)</sup>	NC/TDI <sup>(2)</sup>	NC/TCK <sup>(2)</sup>	NC/TDO <sup>(2)</sup>	NC/TRST <sup>(2,4)</sup>	VDDQ

5297 dw 04

## Top View

### NOTES:

1. R5 can either be directly connected to Vdd, or connected to an input voltage  $\geq V_{IH}$ , or left unconnected.
2. These pins are NC for the "S" version or the JTAG signal listed for the "SA" version. Note: If NC, these pins can either be tied to Vss, Vdd or left floating.
3. T7 can be left unconnected and the device will always remain in active mode.
4. TRST is offered as an optional JTAG Reset if required in the application. If not needed, can be left floating and will internally be pulled to Vdd.

## Pin Configuration – 128K x 36, 165 fBGA

	1	2	3	4	5	6	7	8	9	10	11
A	NC <sup>(4)</sup>	A7	$\overline{CE}_1$	$\overline{BW}_3$	$\overline{BW}_2$	$\overline{CS}_1$	$\overline{BWE}$	$\overline{ADSC}$	$\overline{ADV}$	A8	NC
B	NC	A6	CS0	$\overline{BW}_4$	$\overline{BW}_1$	CLK	$\overline{GW}$	$\overline{OE}$	$\overline{ADSP}$	A9	NC <sup>(4)</sup>
C	I/O <sub>3</sub>	NC	V <sub>DDQ</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DDQ</sub>	NC	I/O <sub>2</sub>	
D	I/O <sub>17</sub>	I/O <sub>16</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	I/O <sub>15</sub>	I/O <sub>14</sub>	
E	I/O <sub>19</sub>	I/O <sub>18</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	I/O <sub>13</sub>	I/O <sub>12</sub>	
F	I/O <sub>21</sub>	I/O <sub>20</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	I/O <sub>11</sub>	I/O <sub>10</sub>	
G	I/O <sub>23</sub>	I/O <sub>22</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	I/O <sub>9</sub>	I/O <sub>8</sub>	
H	V <sub>DD</sub> <sup>(1)</sup>	NC	NC	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	NC	NC	ZZ <sup>(3)</sup>	
J	I/O <sub>25</sub>	I/O <sub>24</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	I/O <sub>7</sub>	I/O <sub>6</sub>	
K	I/O <sub>27</sub>	I/O <sub>26</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	I/O <sub>5</sub>	I/O <sub>4</sub>	
L	I/O <sub>29</sub>	I/O <sub>28</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	I/O <sub>3</sub>	I/O <sub>2</sub>	
M	I/O <sub>31</sub>	I/O <sub>30</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	I/O <sub>1</sub>	I/O <sub>0</sub>	
N	I/O <sub>4</sub>	NC	V <sub>DDQ</sub>	V <sub>SS</sub>	NC/ $\overline{TRST}^{(2,5)}$	NC <sup>(4)</sup>	NC	V <sub>SS</sub>	V <sub>DDQ</sub>	NC	I/O <sub>1</sub>
P	NC	NC <sup>(4)</sup>	A <sub>5</sub>	A <sub>2</sub>	NC/TDI <sup>(2)</sup>	A <sub>1</sub>	NC/TDO <sup>(2)</sup>	A <sub>10</sub>	A <sub>13</sub>	A <sub>14</sub>	NC <sup>(4)</sup>
R	LBO	NC <sup>(4)</sup>	A <sub>4</sub>	A <sub>3</sub>	NC/TMS <sup>(2)</sup>	A <sub>0</sub>	NC/TCK <sup>(2)</sup>	A <sub>11</sub>	A <sub>12</sub>	A <sub>15</sub>	A <sub>16</sub>

5297tbl 17

### NOTES:

1. H1 can either be directly connected to V<sub>DD</sub>, or connected to an input voltage  $\geq V_{IH}$ , or left unconnected.
2. These pins are NC for the "S" version or the JTAG signal listed for the "SA" version. Note: If NC, these pins can either be tied to V<sub>SS</sub>, V<sub>DD</sub> or left floating.
3. H11 can be left unconnected and the device will always remain in active mode.
4. Pins P11, N6, B11, A1, R2 and P2 are reserved for 9M, 18M, 36M, 72M, 144M and 288M respectively.
5.  $\overline{TRST}$  is offered as an optional JTAG Reset if required in the application. If not needed, can be left floating and will internally be pulled to V<sub>DD</sub>.

## DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range ( $V_{DD} = 3.3V \pm 5\%$ )

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
$ I_U $	Input Leakage Current	$V_{DD} = \text{Max.}$ , $V_{IN} = 0V$ to $V_{DD}$	—	5	$\mu A$
$ I_{ZZ} $	$ZZ$ , $\overline{LB_O}$ and JTAG Input Leakage Current <sup>(1)</sup>	$V_{DD} = \text{Max.}$ , $V_{IN} = 0V$ to $V_{DD}$	—	30	$\mu A$
$ I_{OL} $	Output Leakage Current	$V_{OUT} = 0V$ to $V_{DDQ}$ , Device Deselected	—	5	$\mu A$
$V_{OL}$	Output Low Voltage	$I_{OL} = +6mA$ , $V_{DD} = \text{Min.}$	—	0.4	V
$V_{OH}$	Output High Voltage	$I_{OH} = -6mA$ , $V_{DD} = \text{Min.}$	2.0	—	V

NOTE:

5297 tbl 08

- The  $\overline{LB_O}$ , TMS, TDI, TCK and TRST pins will be internally pulled to  $V_{DD}$  and the  $ZZ$  pin will be internally pulled to  $V_{SS}$  if they are not actively driven in the application.

## DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range<sup>(1)</sup>

Symbol	Parameter	Test Conditions	200MHz	183MHz		166MHz		Unit
			Com'l Only	Com'l	Ind	Com'l	Ind	
$I_{DD}$	Operating Power Supply Current	Device Selected, Outputs Open, $V_{DD} = \text{Max.}$ , $V_{DDQ} = \text{Max.}$ , $V_{IN} \geq V_{IH}$ or $\leq V_{IL}$ , $f = f_{MAX}^{(2)}$	360	340	350	320	330	mA
$I_{SB1}$	CMOS Standby Power Supply Current	Device Deselected, Outputs Open, $V_{DD} = \text{Max.}$ , $V_{DDQ} = \text{Max.}$ , $V_{IN} \geq V_{HD}$ or $\leq V_{LD}$ , $f = 0^{(2,3)}$	30	30	35	30	35	mA
$I_{SB2}$	Clock Running Power Supply Current	Device Deselected, Outputs Open, $V_{DD} = \text{Max.}$ , $V_{DDQ} = \text{Max.}$ , $V_{IN} \geq V_{HD}$ or $\leq V_{LD}$ , $f = f_{MAX}^{(2,3)}$	130	120	130	110	120	mA
$I_{ZZ}$	Full Sleep Mode Supply Current	$ZZ \geq V_{HD}$ , $V_{DD} = \text{Max.}$	30	30	35	30	35	mA

NOTES:

5297 tbl 09

- All values are maximum guaranteed values.
- At  $f = f_{MAX}$ , inputs are cycling at the maximum frequency of read cycles of  $1/t_{cyc}$  while  $\overline{ADSC} = \text{LOW}$ ;  $f=0$  means no input lines are changing.
- For I/Os  $V_{HD} = V_{DDQ} - 0.2V$ ,  $V_{LD} = 0.2V$ . For other inputs  $V_{HD} = V_{DD} - 0.2V$ ,  $V_{LD} = 0.2V$ .

## AC Test Conditions ( $V_{DDQ} = 2.5V$ )

Input Pulse Levels	0 to 2.5V
Input Rise/Fall Times	2ns
Input Timing Reference Levels	$(V_{DDQ}/2)$
Output Timing Reference Levels	$(V_{DDQ}/2)$
AC Test Load	See Figure 1

5297tbl 10

## AC Test Load

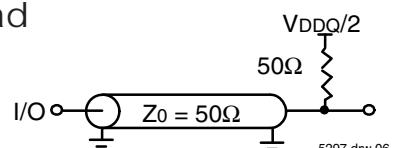


Figure 1. AC Test Load

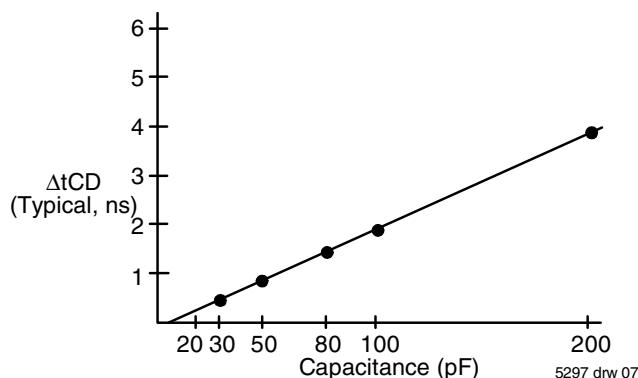


Figure 2. Lumped Capacitive Load, Typical Derating

### Synchronous Truth Table<sup>(1,3)</sup>

Operation	Address Used	$\overline{CE}$	$CS_0$	$\overline{CS}_1$	$\overline{ADSP}$	$\overline{ADSC}$	$\overline{ADV}$	$\overline{GW}$	$\overline{BWE}$	$\overline{BWx}$	$\overline{OE}$ (2)	CLK	I/O	
Deselected Cycle, Power Down	None	H	X	X	X	L	X	X	X	X	X	-	Hi-Z	
Deselected Cycle, Power Down	None	L	X	H	L	X	X	X	X	X	X	-	Hi-Z	
Deselected Cycle, Power Down	None	L	L	X	L	X	X	X	X	X	X	-	Hi-Z	
Deselected Cycle, Power Down	None	L	X	H	X	L	X	X	X	X	X	-	Hi-Z	
Deselected Cycle, Power Down	None	L	L	X	X	L	X	X	X	X	X	-	Hi-Z	
Read Cycle, Begin Burst	External	L	H	L	L	X	X	X	X	X	L	-	DOUT	
Read Cycle, Begin Burst	External	L	H	L	L	X	X	X	X	X	H	-	Hi-Z	
Read Cycle, Begin Burst	External	L	H	L	H	L	X	H	H	X	L	-	DOUT	
Read Cycle, Begin Burst	External	L	H	L	H	L	X	H	L	H	L	-	DOUT	
Read Cycle, Begin Burst	External	L	H	L	H	L	X	H	L	H	H	-	Hi-Z	
Write Cycle, Begin Burst	External	L	H	L	H	L	X	H	L	L	X	-	DIN	
Write Cycle, Begin Burst	External	L	H	L	H	L	X	L	X	X	X	-	DIN	
Read Cycle, Continue Burst	Next	X	X	X	H	H	L	H	H	X	L	-	DOUT	
Read Cycle, Continue Burst	Next	X	X	X	H	H	L	H	H	X	H	-	Hi-Z	
Read Cycle, Continue Burst	Next	X	X	X	H	H	L	H	X	H	L	-	DOUT	
Read Cycle, Continue Burst	Next	X	X	X	H	H	L	H	X	H	H	-	Hi-Z	
Read Cycle, Continue Burst	Next	H	X	X	X	H	L	H	H	X	L	-	DOUT	
Read Cycle, Continue Burst	Next	H	X	X	X	H	L	H	H	X	H	-	Hi-Z	
Read Cycle, Continue Burst	Next	H	X	X	X	H	L	H	X	H	L	-	DOUT	
Read Cycle, Continue Burst	Next	H	X	X	X	H	L	H	X	H	H	-	Hi-Z	
Write Cycle, Continue Burst	Next	X	X	X	H	H	L	H	L	L	X	-	DIN	
Write Cycle, Continue Burst	Next	X	X	X	H	H	L	L	X	X	X	-	DIN	
Write Cycle, Continue Burst	Next	H	X	X	X	H	L	H	L	L	X	-	DIN	
Write Cycle, Continue Burst	Next	H	X	X	X	H	L	L	X	X	X	-	DIN	
Read Cycle, Suspend Burst	Current	X	X	X	H	H	H	H	H	X	L	-	DOUT	
Read Cycle, Suspend Burst	Current	X	X	X	H	H	H	H	H	X	H	-	Hi-Z	
Read Cycle, Suspend Burst	Current	X	X	X	H	H	H	H	H	X	H	-	DOUT	
Read Cycle, Suspend Burst	Current	X	X	X	H	H	H	H	H	X	H	-	Hi-Z	
Read Cycle, Suspend Burst	Current	H	X	X	X	H	H	H	H	H	X	L	-	DOUT
Read Cycle, Suspend Burst	Current	H	X	X	X	H	H	H	H	H	X	H	-	Hi-Z
Read Cycle, Suspend Burst	Current	H	X	X	X	H	H	H	H	X	H	L	-	DOUT
Read Cycle, Suspend Burst	Current	H	X	X	X	H	H	H	H	X	H	H	-	Hi-Z
Write Cycle, Suspend Burst	Current	X	X	X	H	H	H	H	H	L	L	X	-	DIN
Write Cycle, Suspend Burst	Current	X	X	X	H	H	H	H	H	L	X	X	-	DIN
Write Cycle, Suspend Burst	Current	H	X	X	X	H	H	H	H	L	L	X	-	DIN
Write Cycle, Suspend Burst	Current	H	X	X	X	H	H	H	H	L	X	X	-	DIN
Write Cycle, Suspend Burst	Current	H	X	X	X	H	H	H	H	L	X	X	-	DIN

NOTES:

1. L =  $V_{IL}$ , H =  $V_{IH}$ , X = Don't Care.
2.  $\overline{OE}$  is an asynchronous input.
3. ZZ = low for this table.

5297tbl11

### Synchronous Write Function Truth Table<sup>(1)</sup>

Operation	$\overline{GW}$	$\overline{BWE}$	$\overline{BW}_1$	$\overline{BW}_2$	$\overline{BW}_3$	$\overline{BW}_4$
Read	H	H	X	X	X	X
Read	H	L	H	H	H	H
Write all Bytes	L	X	X	X	X	X
Write all Bytes	H	L	L	L	L	L
Write Byte 1 <sup>(2)</sup>	H	L	L	H	H	H
Write Byte 2 <sup>(3)</sup>	H	L	H	L	H	H
Write Byte 3 <sup>(3)</sup>	H	L	H	H	L	H
Write Byte 4 <sup>(3)</sup>	H	L	H	H	H	L

5297 tbl 12

NOTES:

1. L = V<sub>IL</sub>, H = V<sub>IH</sub>, X = Don't Care.
3. Multiple bytes may be selected during the same cycle.

### Asynchronous Truth Table<sup>(1)</sup>

Operation <sup>(2)</sup>	$\overline{OE}$	ZZ	I/O Status	Power
Read	L	L	Data Out	Active
Read	H	L	High-Z	Active
Write	X	L	High-Z - Data In	Active
Deselected	X	L	High-Z	Standby
Sleep Mode	X	H	High-Z	Sleep

5297 tbl 13

NOTES:

1. L = V<sub>IL</sub>, H = V<sub>IH</sub>, X = Don't Care.
2. Synchronous function pins must be biased appropriately to satisfy operation requirements.

### Interleaved Burst Sequence Table ( $\overline{LBO} = VDD$ )

	Sequence 1		Sequence 2		Sequence 3		Sequence 4	
	A1	A0	A1	A0	A1	A0	A1	A0
First Address	0	0	0	1	1	0	1	1
Second Address	0	1	0	0	1	1	1	0
Third Address	1	0	1	1	0	0	0	1
Fourth Address <sup>(1)</sup>	1	1	1	0	0	1	0	0

5297 tbl 14

NOTE:

1. Upon completion of the Burst sequence the counter wraps around to its initial state.

### Linear Burst Sequence Table ( $\overline{LBO} = VSS$ )

	Sequence 1		Sequence 2		Sequence 3		Sequence 4	
	A1	A0	A1	A0	A1	A0	A1	A0
First Address	0	0	0	1	1	0	1	1
Second Address	0	1	1	0	1	1	0	0
Third Address	1	0	1	1	0	0	0	1
Fourth Address <sup>(1)</sup>	1	1	0	0	0	1	1	0

5297 tbl 15

NOTE:

1. Upon completion of the Burst sequence the counter wraps around to its initial state.

## AC Electrical Characteristics

(V<sub>DD</sub> = 3.3V ±5%, Commercial and Industrial Temperature Ranges)

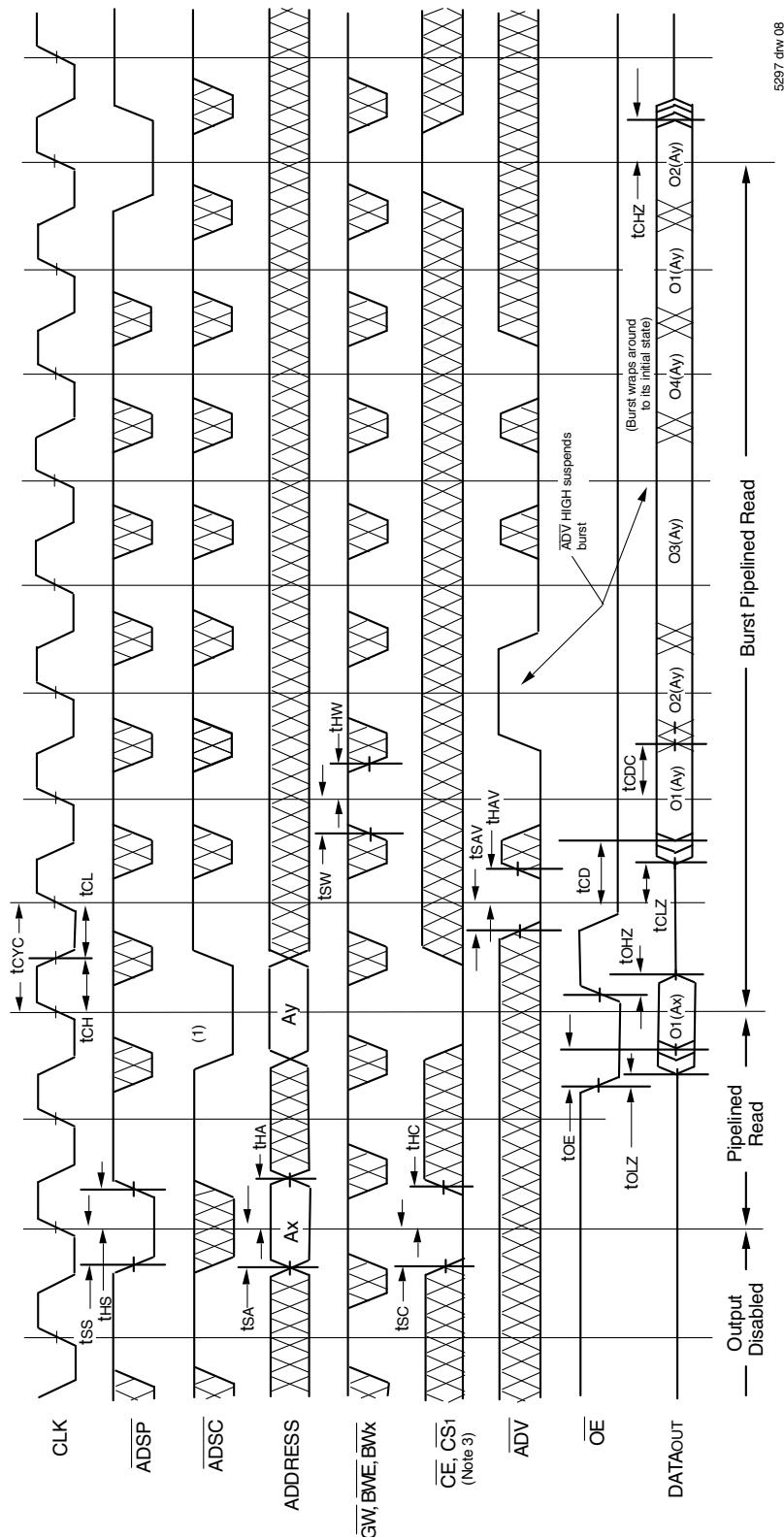
Symbol	Parameter	200MHz <sup>(5)</sup>		183MHz		166MHz		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>CYC</sub>	Clock Cycle Time	5	—	5.5	—	6	—	ns
t <sub>CH</sub> <sup>(1)</sup>	Clock High Pulse Width	2	—	2.2	—	2.4	—	ns
t <sub>CL</sub> <sup>(1)</sup>	Clock Low Pulse Width	2	—	2.2	—	2.4	—	ns
<b>Output Parameters</b>								
t <sub>CD</sub>	Clock High to Valid Data	—	3.1	—	3.3	—	3.5	ns
t <sub>CDC</sub>	Clock High to Data Change	1.0	—	1.0	—	1.0	—	ns
t <sub>CLZ</sub> <sup>(2)</sup>	Clock High to Output Active	0	—	0	—	0	—	ns
t <sub>CHZ</sub> <sup>(2)</sup>	Clock High to Data High-Z	1.5	3.1	1.5	3.3	1.5	3.5	ns
t <sub>OE</sub>	Output Enable Access Time	—	3.1	—	3.3	—	3.5	ns
t <sub>OLZ</sub> <sup>(2)</sup>	Output Enable Low to Output Active	0	—	0	—	0	—	ns
t <sub>OHZ</sub> <sup>(2)</sup>	Output Enable High to Output High-Z	—	3.1	—	3.3	—	3.5	ns
<b>Set Up Times</b>								
t <sub>SA</sub>	Address Setup Time	1.2	—	1.5	—	1.5	—	ns
t <sub>S</sub>	Address Status Setup Time	1.2	—	1.5	—	1.5	—	ns
t <sub>SD</sub>	Data In Setup Time	1.2	—	1.5	—	1.5	—	ns
t <sub>SW</sub>	Write Setup Time	1.2	—	1.5	—	1.5	—	ns
t <sub>SAV</sub>	Address Advance Setup Time	1.2	—	1.5	—	1.5	—	ns
t <sub>SC</sub>	Chip Enable/Select Setup Time	1.2	—	1.5	—	1.5	—	ns
<b>Hold Times</b>								
t <sub>HA</sub>	Address Hold Time	0.4	—	0.5	—	0.5	—	ns
t <sub>HS</sub>	Address Status Hold Time	0.4	—	0.5	—	0.5	—	ns
t <sub>HD</sub>	Data In Hold Time	0.4	—	0.5	—	0.5	—	ns
t <sub>HW</sub>	Write Hold Time	0.4	—	0.5	—	0.5	—	ns
t <sub>HAV</sub>	Address Advance Hold Time	0.4	—	0.5	—	0.5	—	ns
t <sub>HC</sub>	Chip Enable/Select Hold Time	0.4	—	0.5	—	0.5	—	ns
<b>Sleep Mode and Configuration Parameters</b>								
t <sub>ZZPW</sub>	ZZ Pulse Width	100	—	100	—	100	—	ns
t <sub>ZZR</sub> <sup>(3)</sup>	ZZ Recovery Time	100	—	100	—	100	—	ns
t <sub>CFG</sub> <sup>(4)</sup>	Configuration Set-up Time	20	—	22	—	24	—	ns

4876 tbl 16

### NOTES:

1. Measured as HIGH above V<sub>IH</sub> and LOW below V<sub>IL</sub>.
2. Transition is measured ±200mV from steady-state.
3. Device must be deselected when powered-up from sleep mode.
4. t<sub>CFG</sub> is the minimum time required to configure the device based on the  $\overline{LB0}$  input.  $\overline{LB0}$  is a static input and must not change during normal operation.
5. Commercial temperature range only.

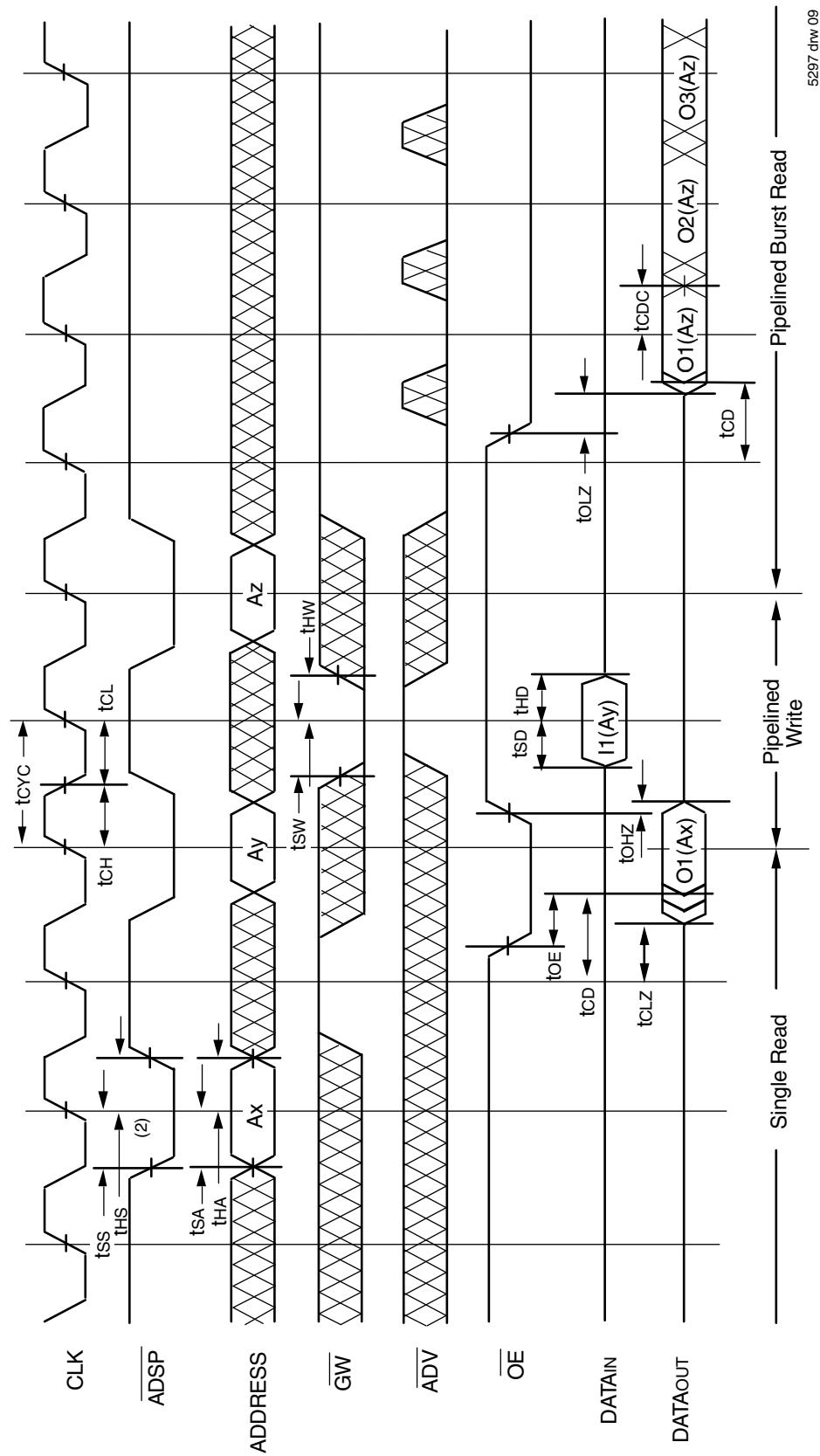
## Timing Waveform of Pipeline Read Cycle<sup>(1,2)</sup>



### NOTES:

1. O1(Ax) represents the first output from the external address Ax. O1(Ay) represents the first output from the external address Ay. O2(Ay) represents the next output data in the burst sequence of the base address Ay, etc. where A0 and A1 are advancing for the four word burst in the sequence defined by the state of the LBO input.
2. ZZ input is LOW and LBO is Don't Care for this cycle.
3. CS<sub>0</sub> timing transitions are identical but inverted to the CE and CS<sub>1</sub> signals. For example, when CE and CS<sub>1</sub> are LOW on this waveform, CS<sub>0</sub> is HIGH.

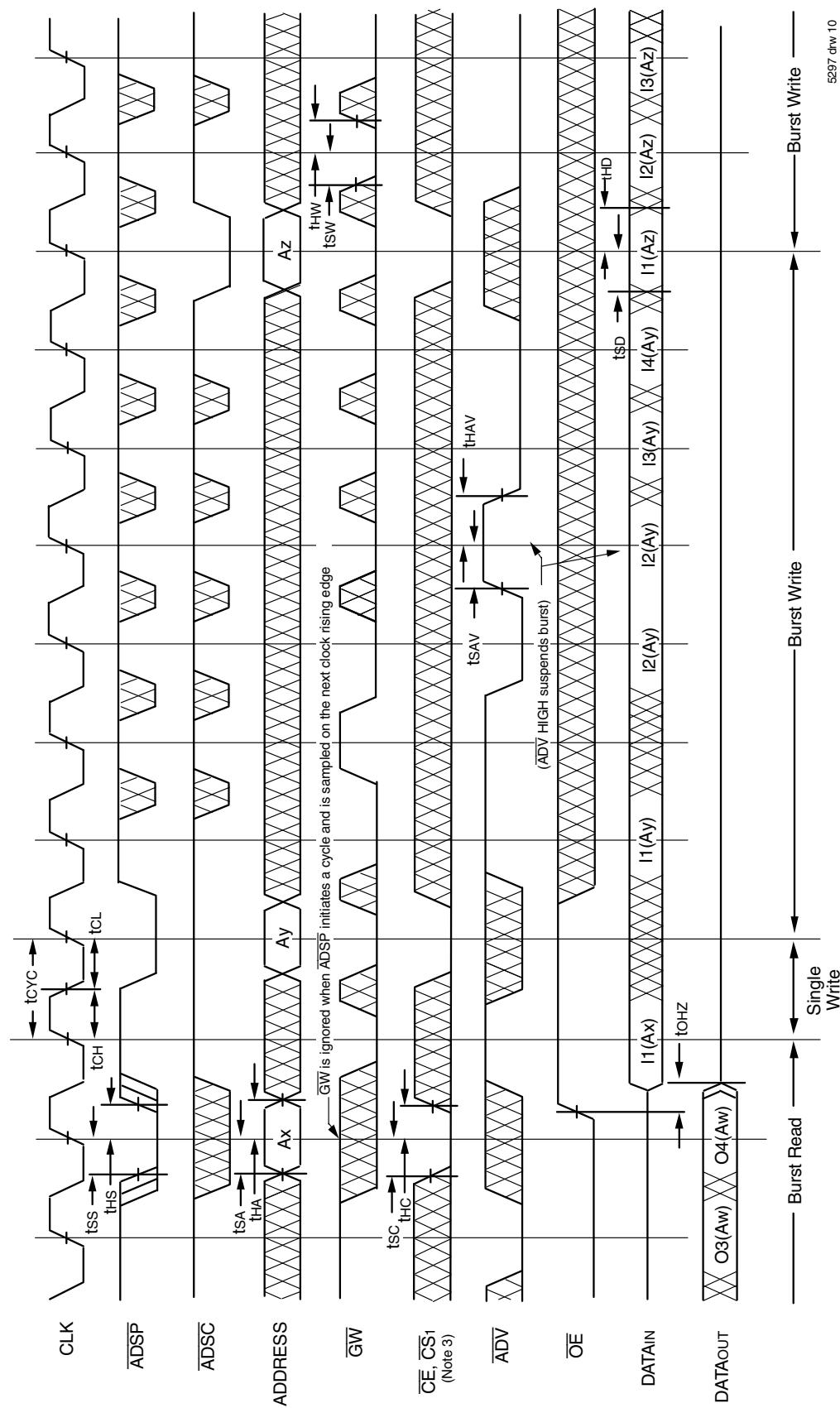
## Timing Waveform of Combined Pipelined Read and Write Cycles<sup>(1,2,3)</sup>



### NOTES:

1. Device is selected through entire cycle:  $\overline{OE}$  and  $\overline{CS}_1$  are LOW,  $CS_0$  is HIGH.
2. ZZ Input is LOW and  $\overline{LB}_0$  Don't Care for this cycle.
3. O1(Ay) represents the first output from the external address Ay; O1(Az) represents the first output from the external address Az. etc. where A0 and A1 are advancing for the forward burst in the sequence defined by the state of the  $\overline{LB}_0$  input.

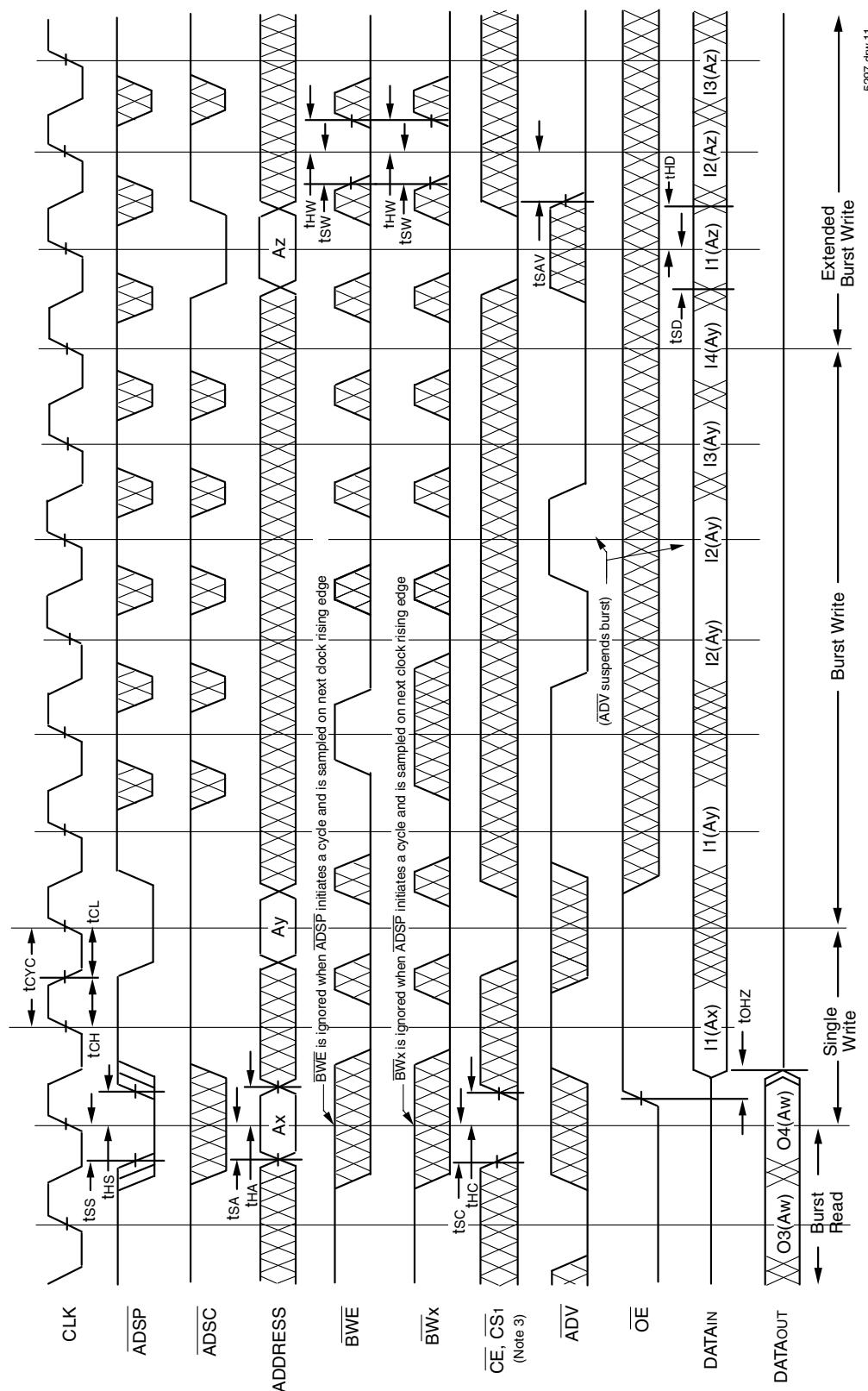
## Timing Waveform of Write Cycle No. 1 — **GW** Controlled<sup>(1,2,3)</sup>



**NOTES:**

1. ZZ input is LOW,  $\overline{BWE}$  is HIGH and  $\overline{LBO}$  is Don't Care for this cycle.
2. O4 (Aw) represents the final output data in the burst sequence of the base address Aw. I1 (Ay) represents the first input from the external address Ay. I2 (Ay) represents the next input data in the burst sequence of the base address Ay, etc. where A0 and A1 are advancing for the four word burst in the sequence defined by the state of the  $\overline{LBO}$  input. In the case of input I2 (Ay) this data is valid for two cycles because  $\overline{ADV}$  is high and has suspended the burst.
3. CS<sub>0</sub> timing transitions are identical but inverted to the  $\overline{OE}$  and  $\overline{CS}_1$  signals. For example, when  $\overline{OE}$  and  $\overline{CS}_1$  are LOW on this waveform, CS<sub>0</sub> is HIGH.

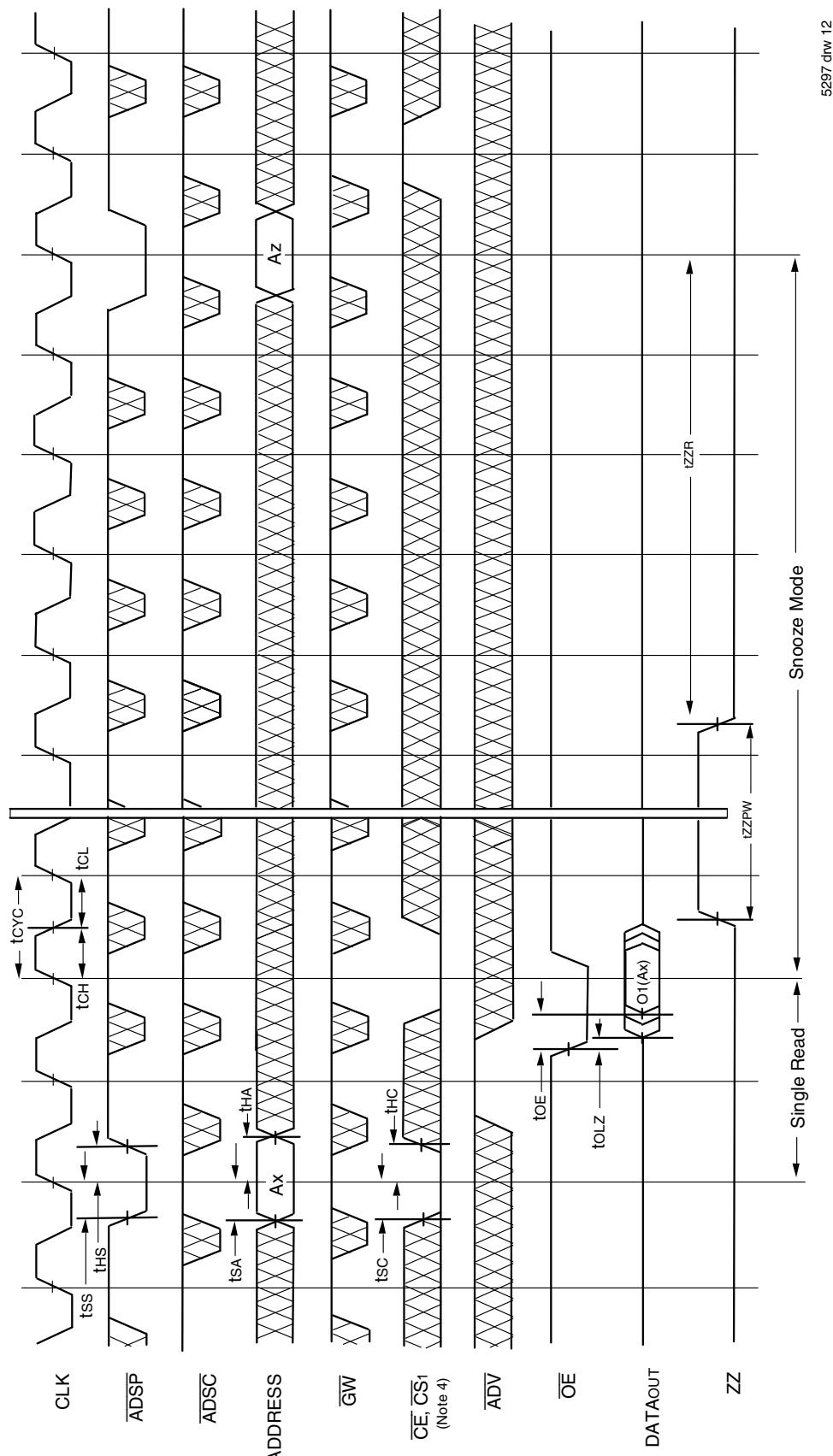
## Timing Waveform of Write Cycle No. 2 — Byte Controlled<sup>(1,2,3)</sup>



**NOTES:**

1. ZZ input is LOW,  $\overline{GW}$  is HIGH and  $\overline{BO}$  is Don't Care for this cycle.
2. O4 (Aw) represents the final output data in the burst sequence of the base address Aw. 11 (Ay) represents the first input from the external address Aw. 11 (Ay) represents the first input from the external address Ay. 12 (Ay) represents the next input data in the burst sequence of the base address Ay, etc. where A0 and A1 are advancing for the four word burst in the sequence defined by the state of the  $\overline{BO}$  input. In the case of input 12 (Ay) this data is valid for two cycles because  $\overline{ADV}$  is high and has suspended the burst.
3. CS0 timing transitions are identical but inverted to the  $\overline{CE}$  and  $\overline{CS}_1$  signals. For example, when  $\overline{CE}$  and  $\overline{CS}_1$  are LOW on this waveform, CS0 is HIGH.

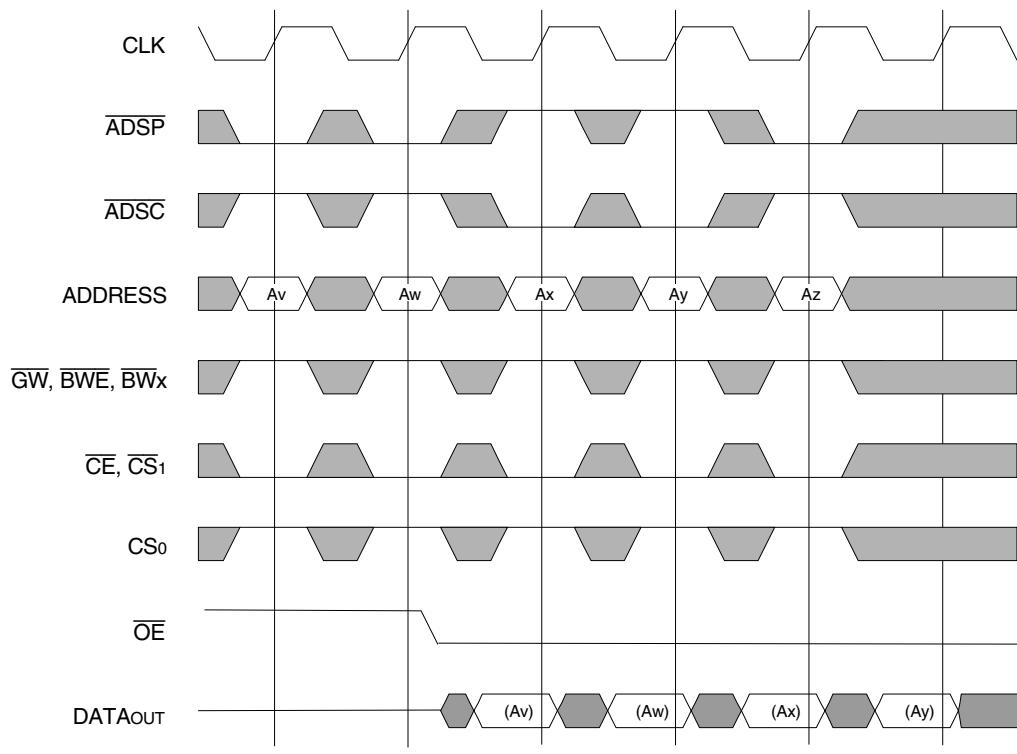
## Timing Waveform of Sleep (ZZ) and Power-Down Modes<sup>(1,2,3)</sup>



**NOTES:**

1. Device must power up in deselected Mode.
2.  $\overline{LBO}$  is Don't Care for this cycle.
3. It is not necessary to retain the state of the input registers throughout the Power-down cycle.
4. CS0 timing transitions are identical but inverted to the CE and CS1 signals. For example, when CE and CS1 are LOW on this waveform, CS0 is HIGH.

## Non-Burst Read Cycle Timing Waveform

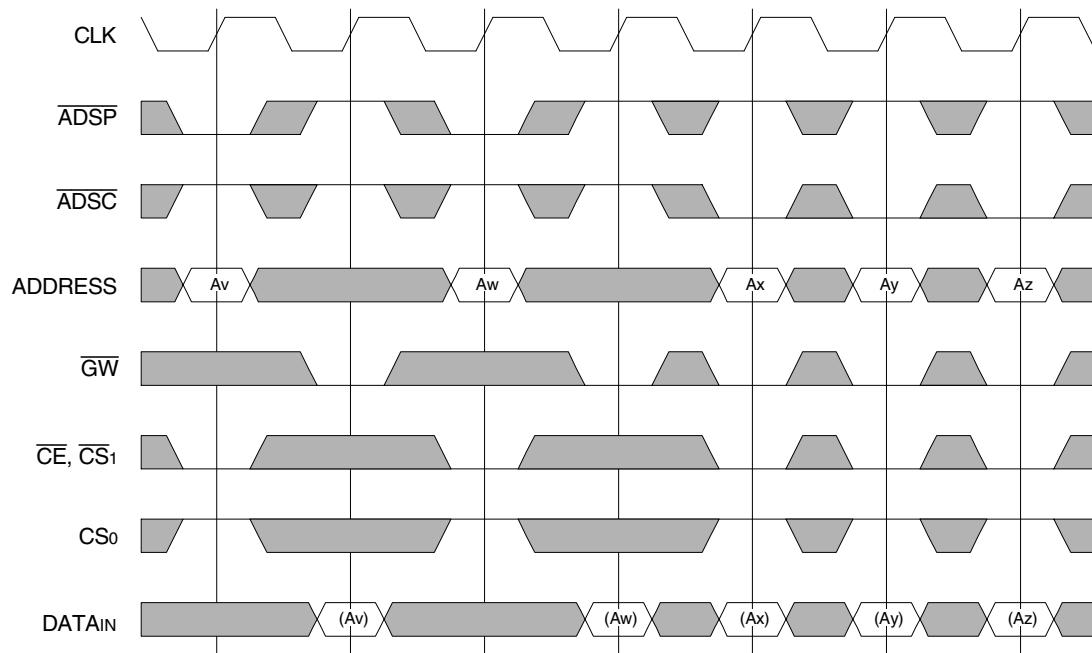


5297 drw 14

### NOTES:

1. ZZ input is LOW,  $\overline{ADV}$  is HIGH and  $\overline{LBO}$  is Don't Care for this cycle.
2. (Ax) represents the data for address Ax, etc.
3. For read cycles,  $\overline{ADSP}$  and  $\overline{ADSC}$  function identically and are therefore interchangeable.

## Non-Burst Write Cycle Timing Waveform

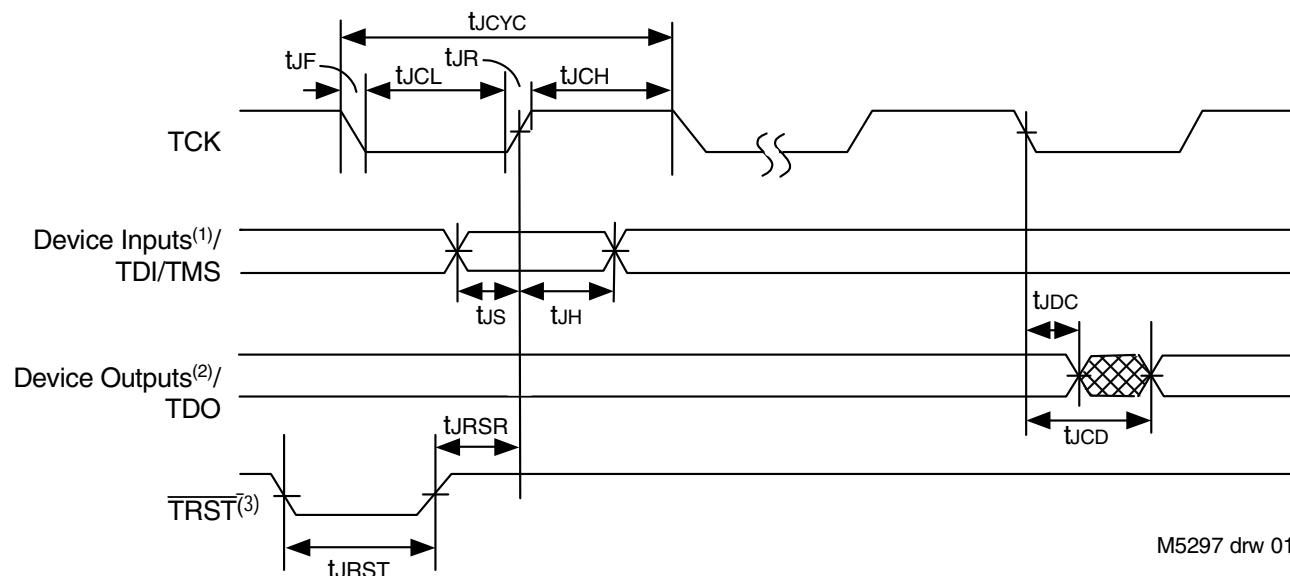


5297 drw 15

### NOTES:

1. ZZ input is LOW,  $\overline{ADV}$  and  $\overline{OE}$  are HIGH, and  $\overline{LBO}$  is Don't Care for this cycle.
2. (Ax) represents the data for address Ax, etc.
3. Although only  $\overline{GW}$  writes are shown, the functionality of  $\overline{BWE}$  and  $\overline{BWx}$  together is the same as  $\overline{GW}$ .
4. For write cycles,  $\overline{ADSP}$  and  $\overline{ADSC}$  have different limitations.

## JTAG Interface Specification (SA Version only)



M5297 drw 01

### NOTES:

1. Device inputs = All device inputs except TDI, TMS and  $\overline{\text{TRST}}$ .
2. Device outputs = All device outputs except TDO.
3. During power up,  $\overline{\text{TRST}}$  could be driven low or not be used since the JTAG circuit resets automatically.  $\overline{\text{TRST}}$  is an optional JTAG reset.

## JTAG AC Electrical Characteristics<sup>(1,2,3,4)</sup>

Symbol	Parameter			
		Min.	Max.	Units
t <sub>CYC</sub>	JTAG Clock Input Period	100	—	ns
t <sub>CH</sub>	JTAG Clock HIGH	40	—	ns
t <sub>CL</sub>	JTAG Clock Low	40	—	ns
t <sub>R</sub>	JTAG Clock Rise Time	—	5 <sup>(1)</sup>	ns
t <sub>F</sub>	JTAG Clock Fall Time	—	5 <sup>(1)</sup>	ns
t <sub>_RST</sub>	JTAG Reset	50	—	ns
t <sub>RSR</sub>	JTAG Reset Recovery	50	—	ns
t <sub>CD</sub>	JTAG Data Output	—	20	ns
t <sub>OC</sub>	JTAG Data Output Hold	0	—	ns
t <sub>S</sub>	JTAG Setup	25	—	ns
t <sub>H</sub>	JTAG Hold	25	—	ns

I5297 tbl 01

### NOTES:

1. Guaranteed by design.
2. AC Test Load (Fig. 1) on external output signals.
3. Refer to AC Test Conditions stated earlier in this document.
4. JTAG operations occur at one speed (10MHz). The base device may run at any speed specified in this datasheet.

## Scan Register Sizes

Register Name	Bit Size
Instruction (IR)	4
Bypass (BYR)	1
JTAG Identification (JIDR)	32
Boundary Scan (BSR)	Note (1)

I5297tbl 03

### NOTE:

1. The Boundary Scan Descriptive Language (BSDL) file for this device is available by contacting your local IDT sales representative.

## JTAG Identification Register Definitions (SA Version only)

Instruction Field	Value	Description
Revision Number (31:28)	0x2	Reserved for version number.
IDT Device ID (27:12)	0x23D, 0x23F	Defines IDT part number 71V25761SA and 71V25781SA, respectively.
IDT JEDEC ID (11:1)	0x33	Allows unique identification of device vendor as IDT.
ID Register Indicator Bit (Bit 0)	1	Indicates the presence of an ID register.

IS297 Tbl 02

## Available JTAG Instructions

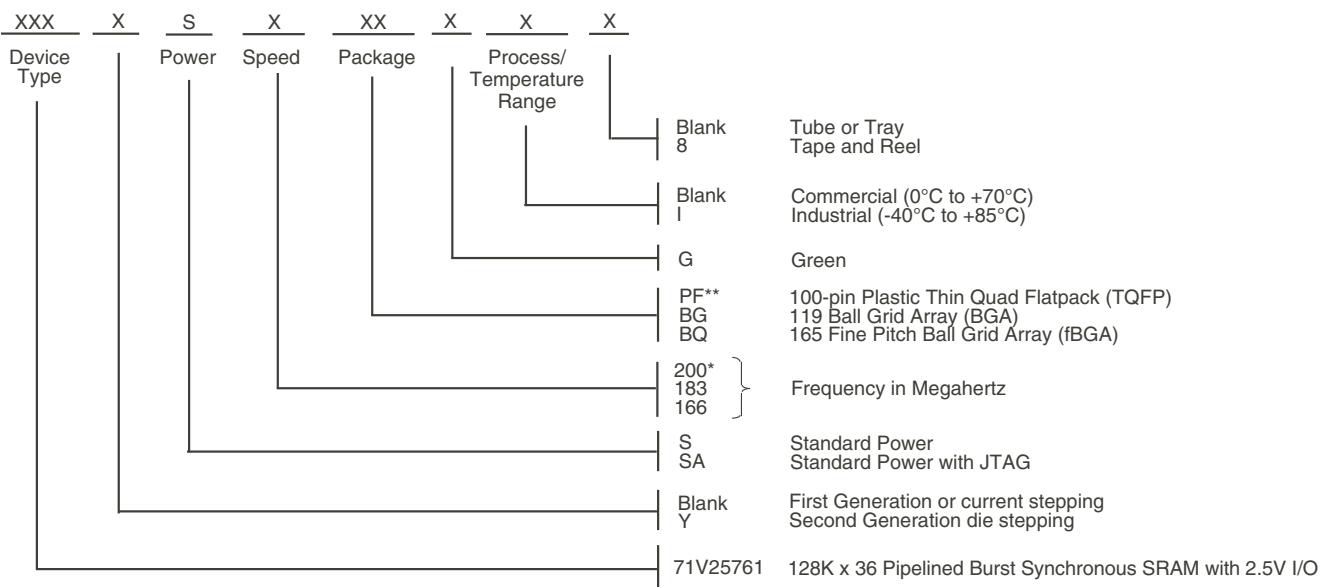
Instruction	Description	OPCODE
EXTEST	Forces contents of the boundary scan cells onto the device outputs <sup>(1)</sup> . Places the boundary scan register (BSR) between TDI and TDO.	0000
SAMPLE/PRELOAD	Places the boundary scan register (BSR) between TDI and TDO. SAMPLE allows data from device inputs <sup>(2)</sup> and outputs <sup>(1)</sup> to be captured in the boundary scan cells and shifted serially through TDO. PRELOAD allows data to be input serially into the boundary scan cells via the TDI.	0001
DEVICE_ID	Loads the JTAG ID register (JIDR) with the vendor ID code and places the register between TDI and TDO.	0010
HIGHZ	Places the bypass register (BYR) between TDI and TDO. Forces all device output drivers to a High-Z state.	0011
RESERVED	Several combinations are reserved. Do not use codes other than those identified for EXTEST, SAMPLE/PRELOAD, DEVICE_ID, HIGHZ, CLAMP, VALIDATE and BYPASS instructions.	0100
RESERVED		0101
RESERVED		0110
RESERVED		0111
CLAMP	Uses BYR. Forces contents of the boundary scan cells onto the device outputs. Places the bypass register (BYR) between TDI and TDO.	1000
RESERVED	Same as above.	1001
RESERVED		1010
RESERVED		1011
RESERVED		1100
VALIDATE	Automatically loaded into the instruction register whenever the TAP controller passes through the CAPTURE-IR state. The lower two bits '01' are mandated by the IEEE std. 1149.1 specification.	1101
RESERVED	Same as above.	1110
BYPASS	The BYPASS instruction is used to truncate the boundary scan register as a single bit in length.	1111

IS297 Tbl 04

### NOTES:

1. Device outputs = All device outputs except TDO.
2. Device inputs = All device inputs except TDI, TMS, and TRST.

## Ordering Information



5297 drw 13

\*Available in commercial range only

\*\* JTAG (SA version) is not available with 100-pin TQFP package

## Package Information

100-Pin Thin Quad Plastic Flatpack (TQFP)  
119 Ball Grid Array (BGA)  
165 Fine Pitch Ball Grid Array (fBGA)  
Information available on the IDT website

## Datasheet Document History

12/31/99	Pg. 1, 4, 8, 19	Created new datasheet from 71V2576 and 71V2578 datasheets
04/04/00	Pg. 18	Added Industrial Temperature range offerings
	Pg. 4	Added 100pin TQFP Package Diagram Outline
		Add capacitance table for BGA package; Add Industrial temperature to table; Insert note to Absolute Max Ratings and Recommended Operating Temperature tables
06/01/00	Pg. 20	Add new package offering, 13 x 15mm 165 fBGA
07/15/00	Pg. 7	Correct BG119 Package Diagram Outline
	Pg. 8	Add note reference to BG119 pinout
	Pg. 20	Add DNU note to BQ165 pinout
10/25/00	Pg. 8	Update BG119 Package Diagram Outline Dimensions
		Remove Preliminary from datasheet
04/22/03	Pg.4	Add reference note to pin N5 in BQ165 pinout, reserved for JTAG, <u>TRST</u>
06/30/03	Pg. 1,2,3,5-9	Updated 165 BGA table information from TBD to 7
	Pg. 5-8	Updated datasheet with JTAG information
	Pg. 19,20	Removed note for NC pins (38,39(PF package); L4, U4 (BG package) H2, N7 (BQ package)) requiring NC or connection to Vss.
	Pg. 21-23	Added two pages of JTAG Specification, AC Electrical, Definitions and Instructions
	Pg. 24	Removed old package information from the datasheet
		Updated ordering information with JTAG and Y stepping information. Added information regarding packages available IDT website.
03/13/09	Pg.21	Removed "IDT" from orderable part number
05/27/10	Pg.20	Added "Restricted hazardous substance device" to the ordering information
	Pg.1-20	Removed IDT71V25781S/SA from datasheet
07/24/14	Pg. 20	Updated Ordering Information changed indicator from "Restricted hazardous substance device" to "Green" and added Tape & Reel



**CORPORATE HEADQUARTERS**  
6024 Silver Creek Valley Road  
San Jose, CA 95138

*for SALES:*  
800-345-7015 or  
408-284-8200  
fax: 408-284-2775  
[www.idt.com](http://www.idt.com)

*for Tech Support:*  
[sramhelp@idt.com](mailto:sramhelp@idt.com)  
408-284-4532

The IDT logo is a registered trademark of Integrated Device Technology, Inc.